

800G OSFP112 Active Electrical Copper Cable

Features

- 8 independent full-duplex passive copper cable transceiver
- Support 112G (PAM4) electrical data rates/channel
- I2C for EEPROM communication
- Pull to Release latch design
- Excellent EMI/EMC performance 360 degree cable shield termination
- Advantage dual side pre-solder automated assembly technologies
- Low loss, stronger mechanical features, more flexible

Standards Compliance

- IEEE802.3ck compliant
- OSFP MSA 5.0 and CMIS 5.1 compliant

Applications

- Data center & Networking Equipment
- Servers/Storage Devices
- High Performance Computing (HPC)
- Switches/Routers

General Description

In an effort to keep up with the demands of higher performance and increasing amounts of memory bus bandwidth, VITAL designers are working to revise, extend and update the solution. VITAL O112 To O112 active Electrical cable assembly can provide new generation performance of OSFP112 by higher data transfer rate.

At the same time, VITAL O112 To O112 AEC cable choose dual side drain cable and self-designed PCBA, provide low loss, less skew and better NEXT. 360 degree EMI crimping shielding and Zinc Die-cast shell designing make the product high-performance. And all the designing is based on the industry standard specifications, such as OSFP CMIS&MSA, VITAL high-quality solutions provide a power efficient replacement for active power connectivity such as fiber optic cables for short distances. Optimizing systems to operate with VITAL Active Electrical Copper cables significantly reduces power consumption and EMI emission.

Part No.	Specifications				
	Package	Data rate	Conductor Size	Temp	Lengths
VE5Q-5QDP007	OSFP-Finned\800 G to 800G	850Gbps	28AWG	0~70℃	7m

1 Absolute Maximum Ratings and Operation Conditions

Table 1.1 Absolute Maximum Ratings

Parameter	Symbol	Unit	Min	Max
Supply Voltage	V _{cc}	V	-0.5	3.6
Storage Temperature	T _{sto}	°C	-40	85
RelativeHumidity (Non-condensing)	RH	%	5	85

Table 1.2 Operating Conditions

Parameter	Symbol	Unit	Min	Typ	Max	NOTE
Power Supply Voltage	V _{cc}	V	3.135	3.3	3.465	
Case Operating Temperature	T _c	°C	0		70	
Power Dissipation	P	W			10	800G, per end
Power Dissipation	P	W			6	400G, per end
Data Rate per Lane		GBd		53.125		
Bit Error Ratio, Pre-FEC				<1E-8		Tested with PRBS31Q
Bit Error Ratio, Post-FEC				<1E-15		Tested with PRBS31Q

2 Pin Descriptions

The OSFP module is based on a 60 pin electrical connector with pin out as specified in OSFP Hardware specification. The 60 electrical pins allow exchanging high speed data, control and alarm signals between module and host board. The pin-outs are summarized below:

Top Side (viewed from top)

60	GND	
59	TX1p	
58	TX1n	
57	GND	
56	TX3p	
55	TX3n	
54	GND	
53	TX5p	
52	TX5n	
51	GND	
50	TX7p	
49	TX7n	
48	GND	
47	SDA	
46	VCC	
45	VCC	
44	INT/RSTn	
43	GND	
42	RX8n	
41	RX8p	
40	GND	
39	RX6n	
38	RX6p	
37	GND	
36	RX4n	
35	RX4p	
34	GND	
33	RX2n	
32	RX2p	
31	GND	

----- Module Card Edge -----

Bottom Side (viewed from bottom)

	GND	1
	TX2p	2
	TX2n	3
	GND	4
	TX4p	5
	TX4n	6
	GND	7
	TX6p	8
	TX6n	9
	GND	10
	TX8p	11
	TX8n	12
	GND	13
	SCL	14
	VCC	15
	VCC	16
	LPWn/PRSn	17
	GND	18
	RX7n	19
	RX7p	20
	GND	21
	RX5n	22
	RX5p	23
	GND	24
	RX3n	25
	RX3p	26
	GND	27
	RX1n	28
	RX1p	29
	GND	30

Figure 2.1 OSFP module pinout

Pad#	Symbol	Description	Logic	Direction	Plug Sequence	Notes
1	GND	Ground				
2	TX2p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
3	TX2n	Transmitter Data Inverted	CML-I	nput from Host	3	
4	GND	Ground			1	
5	TX4p	Transmitter Data Non-Inverted	CML-I	nput from Host	3	
6	TX4n	Transmitter Data Inverted	CML-I	Input from Host	3	
7	GND	Ground			1	
8	TX6p	Transmitter Data Non-Inverted	CML-I	nput from Host	3	
9	TX6n	Transmitter Data Inverted	CML-I	nput from Host	3	
10	GND	Ground			1	
11	TX6p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
12	TX6n	Transmitter Data Inverted	CML-I	nput from Host	3	
13	GND	Ground				
14	SCL	2-wire serial interface clock	LVCMOS-VO	Bi-directional	3	Open-Drain with pull-up resistor on Host
15	VCC	+3.3V Power		Power from Host	2	
16	VCC	+3.3V Power		Power from Host	2	
17	LPWn/PRSn	Low-Power Mode/Module Present	Multi-Level	Bi-directional	3	See pin description for required circuit
18	GND	Ground			1	

19	RX7n	Receiver Data Inverted	CML-O	Output to Host	3	
20	RX7p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
21	GND	Ground				
22	RX5n	Receiver Data Inverted	CML-O	Output to Host	3	
23	RX5p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
24	GND	Ground			1	
25	RX3n	Receiver Data Inverted	CML-O	Output to Host	3	
26	RX3p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
27	GND	Ground				
28	RX1n	Receiver Data Inverted	CML-O	Output to Host	3	
29	RX1p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
30	GND	Ground				
31	GND	Ground				
32	RX2p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
33	RX2n	Receiver Data Inverted	CML-O	Output to Host	3	
34	GND	Ground			1	
35	RX4p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
36	RX4n	Receiver Data Inverted	CML-O	Output to Host	3	
37	GND	Ground			1	
38	RX6p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
39	RX6n	Receiver Data Inverted	CML-O	Output to Host	3	
40	GND	Ground				
41	RX8p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
42	RX8n	Receiver Data Inverted	CML-O	Output to Host	3	
43	GND	Ground				

44	INT/RSTn	Module Interrupt/Module Reset	Multi-Level	Bi-directional	3	See pin description for required circuit
45	VCC	+3.3V Power		Power from Host	2	
46	VCC	+3.3V Power		Power from Host	2	
47	SDA	2-wire serial interface Data	LVC MOS-VO	Bi-directional	3	Open-Drain with pull-up resistor on Host
48	GND	Ground				
49	TX7n	Transmitter Data Inverted	CML-I	Input from Host	3	
50	TX7p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
51	GND	Ground				
52	TX5n	Transmitter Data Inverted	CML-I	Input from Host	3	
53	TX5p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
54	GND	Ground				
55	TX3n	Transmitter Data Inverted	CML-I	Input from Host	3	
56	TX3p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
57	GND	Ground				
58	TX1n	Transmitter Data Inverted	CML-I	Input from Host	3	
59	TX1p	Transmitter Data Non-Inverted	CML-1	Input from Host	3	
60	GND	Ground				

3 Environment Regulation Compliance and product Safety

Category	Standard
Radiated Emissions	EN 55032 Class B CISPR 32 Class B FCC rules 47 CFR Part15

Radiated Immunity	EN 55035 CISPR 35 IEC/EN 61000-4-3
RoHS	EU RoHS 2.0 (2011/65/EU) REACH (EC 1907/2006) China RoHS SJ/T 11363
Laser Safety	IEC 60825-1:2014+A11:2021 FDA/CDRH Class 1 Laser Product, 21 CFR 1040.10 & 1040.11
ESD	IEC 61000-4-2; ANSI/ESDA/JEDEC JS-001; MIL-STD-883C Contact $\pm 8\text{kV}$, Air $\pm 15\text{kV}$
Flammability (PCB)	UL Class 94 V-0
Reliability	GR-468-CORE、IEC 61300-2

4 Important Notice

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5 Revision History

Revision	Date	Description
V1.0	2026.5.21	Advance Release.